Electronic Acknowledgement Receipt				
EFS ID:	1308962			
Application Number:	10813223			
International Application Number:				
Confirmation Number:	3854			
Title of Invention:	METAL LINE HAVING AN INCREASED RESISTANCE TO ELECTROMIGRATION ALONG AN INTERFACE OF A DIELECTRIC BARRIER LAYER BY IMPLANTING MATERIAL INTO THE METAL LINE			
First Named Inventor/Applicant Name:	Hans-Juergen Engelmann			
Customer Number:	23720			
Filer:	J. Mike Amerson/Mary Paul			
Filer Authorized By:	J. Mike Amerson			
Attorney Docket Number:	2000.110900			
Receipt Date:	13-NOV-2006			
Filing Date:	30-MAR-2004			
Time Stamp:	14:42:01			
Application Type:	Utility			

Payment information:

ubmitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part /.zip	Pages (if appl.)
1	Post Allowance Communication - Incoming	Response_to_Examiner_Sta tement_of_Reasons_for_Allo wance.pdf		no	1
Warnings:					

Informa	tion:	
	Total Files Size (in bytes):	60777

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.